

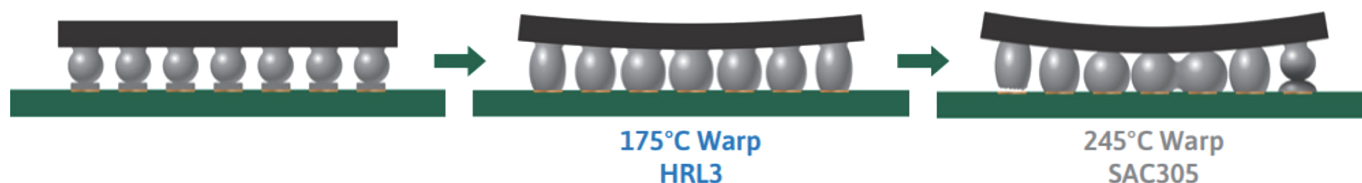
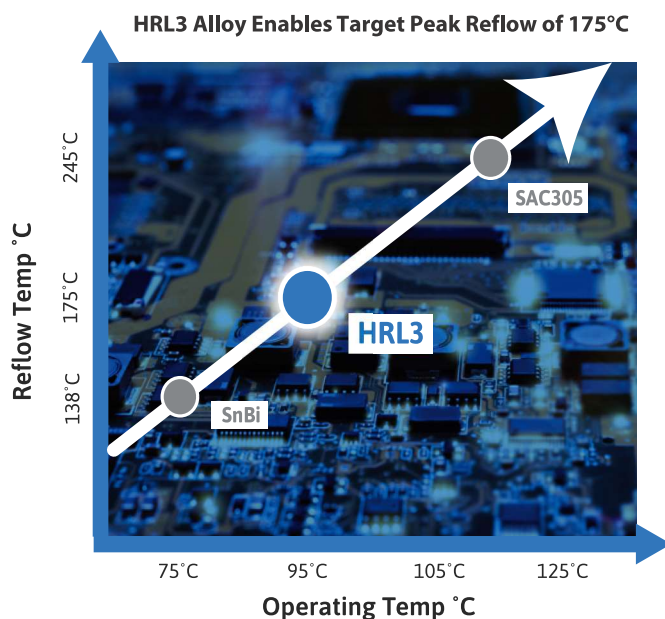
ALPHA[®] OM-565 HRL3

Low Temperature, No-Clean, High Reliability Solder Paste

Enables Lower Peak Reflow, Reduced Total Cost of Ownership, and Minimizes Warpage-Induced Defects.

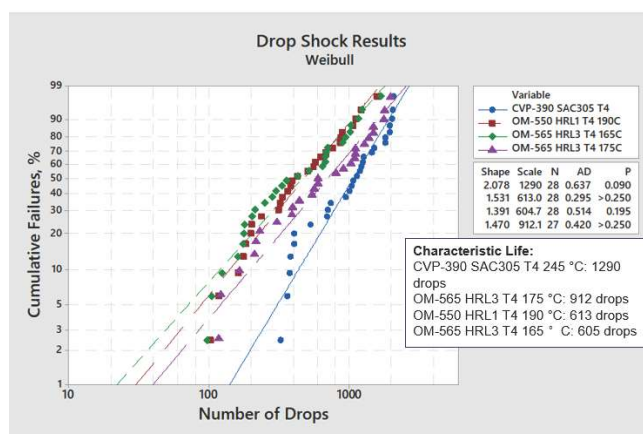
ALPHA OM-565 HRL3 low temperature solder paste is formulated for a broad range of assemblies to mitigate warpage-induced defects in temperature sensitive chip-scale packages.

ALPHA OM-565 HRL3 is designed to enable target reflow temperatures of 175°C with superior wettability to minimize post reflow defects, such as Non-Wet-Open (NWO) and Head-in-Pillow (HIP).



KEY FEATURES

- Comparable thermomechanical reliability to SAC305 for operating temperatures below 100°C
- Compatibility with HRL3 alloy for enhanced drop shock performance
- HRL3 alloy enables peak reflow temperatures of 175°C to mitigate warpage-induced defects
- Superior HIP/NWO performance
- Compatibility with contact rework applications
- 8-hour stencil life in ambient and elevated conditions



Enhanced Drop Shock Performance



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